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ABSTRACT

Kinetic Solder Paste Composition

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A solder paste composition containing (a) 4-96% by weight finely divided particles of eutectic or pseudo-eutectic metal alloy or mixtures; (b) 96-4% by weight finely divided particles of a metal additive consisting of pure metal, mixtures or alloys thereof having a melting point of at least 30°C greater than the metal alloy in (a); and (c) an organic medium. The paste is particularly useful for surface mounting metallized components to metallized substrates in microelectronic packaging.

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